



Product Change Notification

Change Notification #: 115210 - 00
Change Title: 2U Dual Port Hot-swap Drive Cage
Upgrade Kit 8 x 2.5" A2U8X25S3DPDK,
PCN 115210-00,
Product Design, Remove connectors
J3B3 and J3B4

Date of Publication: January 06, 2017

Key Characteristics of the Change:
Product Design

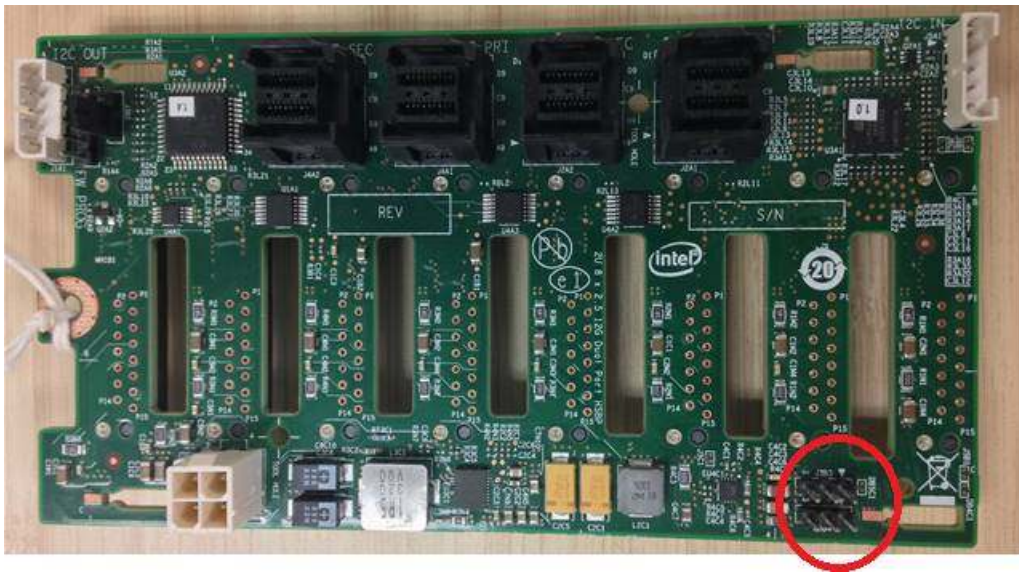
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	January 21, 2017
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel will remove the debug connector J3B3 and J3B4 from the Hot Swap Backplane in the Intel® Server kit A2U8X25S3DPDK. The debug connectors are not required for the proper function of the Intel Server kit.



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
A2U8X25S3DPDK	935067	H47007-003	H47007-004

PCN Revision History:

Date of Revision:

January 06, 2017

Revision Number:

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Reason:

Originally Published PCN



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115210 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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